

Amendments to the Specification:

Please replace the paragraph beginning on page 10, line 5 with the following amended paragraph:

-- The circuit package 100 may further include a heat sink component 200 to provide greater thermal conductivity to the circuit package 100. The heat sink 200 may be, but is not limited to, a copper tungsten (CuW) heat sink 200. The heat sink 200 may be configured as a pedestal block having an upper body portion 210 having a perimeter edge and a top surface 215. The heat sink 200 may further include a lower body portion 220 also having a perimeter edge and a bottom surface 225. Use of terminology such as "upper," "lower," "top" and "bottom" is merely for the sake of describing the figures and is not intended to necessarily be descriptive description of the orientation of the circuit package 100 or its components to any particular orientation and should not be construed as a limitation on the scope of the claims. The top surface 215 of the upper body portion 210 may have a smaller surface area than the bottom surface 225 of the lower body portion 220, such that the lower body portion 220 may act as a flange extending outwardly from the upper body portion 210. --